

EAST - (10050300.wsp:1)

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 (749) microelectronic and optoelectronic
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Default operator: ☒ Highlight all hit terms initially

((microelectronic and optoelectronic) and (substrate and bond adj pad and passivation)) and (aluminum "Al")

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6682659 B1	20040127	16	Method for forming corrosion inhibited conductor layer	216/13	216/67; 216/77;
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6660641 B1	20031209	8	Method for forming crack resistant planarizing layer within microelectronic	438/699	430/314
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6635585 B1	20031021	7	Method for forming patterned polyimide layer	438/780	430/313; 430/317;
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6544878 B2	20030408	10	Microelectronic fabrication having formed therein terminal electrode structure	438/612	257/E21.508; 257/E23.021;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6534396 B1	20030318	11	Patterned conductor layer pasivation method with dimensionally stabilized	438/632	438/631; 438/637;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6448171 B1	20020910	9	Microelectronic fabrication having formed therein terminal electrode structure	438/614	438/612; 438/613;
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6424037 B1	20020723	10	Process to make a tall solder ball by placing a eutectic solder ball on top of a high lead	257/738	257/E21.508; 257/E21.511;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6362087 B1	20020326	9	Method for fabricating a microelectronic fabrication having formed therein a	438/597	257/685; 257/700;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6338976 B1	20020115	8	Method for forming optoelectronic microelectronic fabrication with attenuated	438/48	438/617; 510/176
10	<input type="checkbox"/>	<input type="checkbox"/>	US 6316831 B1	20011113	10	Microelectronic fabrication having formed therein terminal electrode structure	257/737	257/763; 257/764;
11	<input type="checkbox"/>	<input type="checkbox"/>	US 6281041 B1	20010828	10	Process to make a tall solder ball by placing a eutectic solder ball on top of a high lead	438/106	257/E21.508; 257/E21.511;